# NOVEL THERMAL CONTROL CONCEPTS USING MICRO HEAT PIPES - SPACECRAFT THERMAL CONTROL

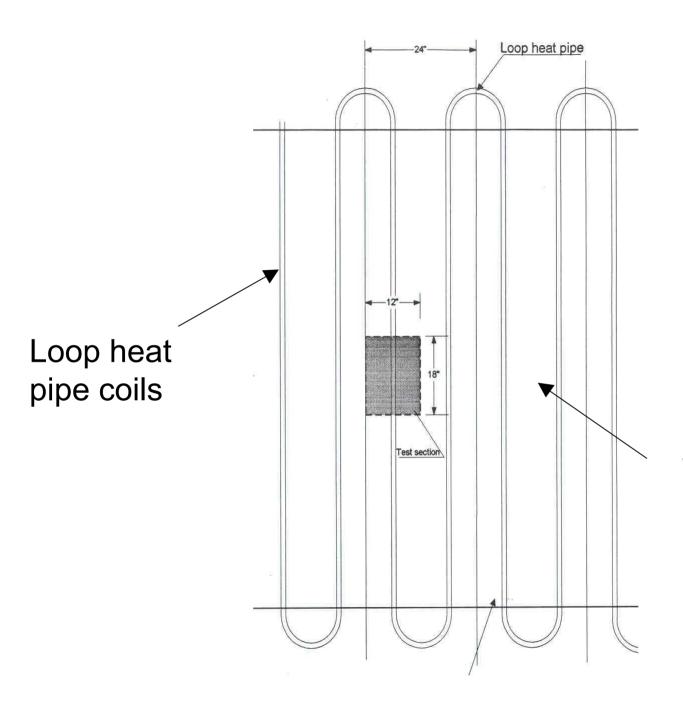
#### G. P. "Bud" Peterson

Department of Mechanical Engineering, Aeronautical Engineering and Mechanics Rensselaer Polytechnic Institute Troy, NY 12180

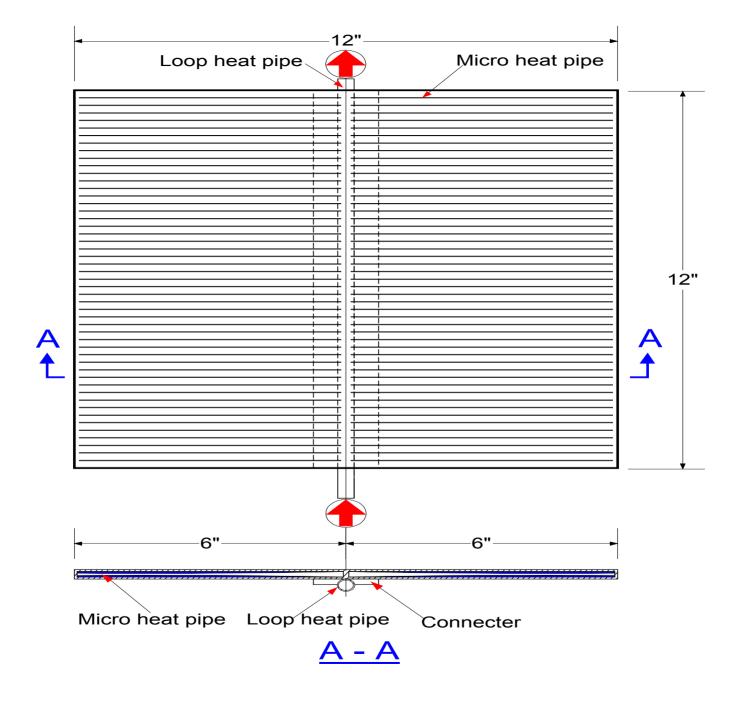
REPORT D		Form Approved OMB No. 0704-0188			
Public reporting burder for this collection of information is estibated to and reviewing this collection of information. Send comments regardin Headquarters Services, Directorate for Information Operations and Re law, no person shall be subject to any penalty for failing to comply wit	g this burden estimate or any other aspect of this colle ports (0704-0188), 1215 Jefferson Davis Highway, S	ection of information, inc uite 1204, Arlington, VA	luding suggestions for reducing 22202-4302. Respondents sho	g this burder to Department of Defense, Washington ould be aware that notwithstanding any other provision of	
1. REPORT DATE (DD-MM-YYYY) 30-05-2001	2. REPORT TYPE Workshop Presentations			COVERED (FROM - TO) to 01-06-2001	
4. TITLE AND SUBTITLE  Novel Thermal Control Concepts Using Micro Heat Pipes - Spacecraft Thermal Control			5a. CONTRACT NUMBER		
			5b. GRANT NUMBER		
Unclassified			5c. PROGRAM I	ELEMENT NUMBER	
6. AUTHOR(S)			5d. PROJECT N	UMBER	
Peterson, G. P.;			5e. TASK NUMBER		
			5f. WORK UNIT	NUMBER	
7. PERFORMING ORGANIZATION NA Department of Mechanical Engineering, Aeronautical Engineering and Mechanics Rensselaer Polytechnic Institute Troy, NY12180	ME AND ADDRESS		8. PERFORMING NUMBER	G ORGANIZATION REPORT	
9. SPONSORING/MONITORING AGENCY NAME AND ADDRESS			10. SPONSOR/MONITOR'S ACRONYM(S)		
Office of Naval Research International Fie Office of Naval Research Washington, DCxxxxx	11. SPONSOR/MONITOR'S REPORT NUMBER(S)				
12. DISTRIBUTION/AVAILABILITY S' APUBLIC RELEASE	FATEMENT				
, 13. SUPPLEMENTARY NOTES See Also ADM001348, Thermal Materials downloaded from: http://www-mech.eng.c		oridge, UK on M	1ay 30-June 1, 200	01. Additional papers can be	
14. ABSTRACT	D 1 116 W D 0D	1 20 11	D' O EMPED	D. CO. VIII. D. L. C. V. MINA	
? MICRO HEAT PIPE CONCEPTS ? Wit	re Bonded Micro Heat Pipe ? Po	olymer Micro H	eat Pipe ? EXPER	IMENT FACILITY	
15. SUBJECT TERMS 16. SECURITY CLASSIFICATION OF	: 17. LIMITATION	l18.	NO NAME OF P	RESPONSIBLE PERSON	
16. SECORITY CLASSIFICATION OF	OF ABSTRACT Public Release	NUMBER	Fenster, Lynn Ifenster@dtic.mi		
a. REPORT  b. ABSTRACT  c. THI Unclassified  Unclassified  Uncla		•	19b. TELEPHONE NUMBER International Area Code Area Code Telephone Number 703767-9007 DSN 427-9007		
				Standard Form 298 (Rev. 8-98) Prescribed by ANSI Std Z39.18	

#### Introduction

- BACKGROUND
- MICRO HEAT PIPE CONCEPTS
  - Wire Bonded Micro Heat Pipe
  - Polymer Micro Heat Pipe
- EXPERIMENT FACILITY
- RESULTS & DISCUSSION
- CONCLUSIONS



Space occupied by flexible fins

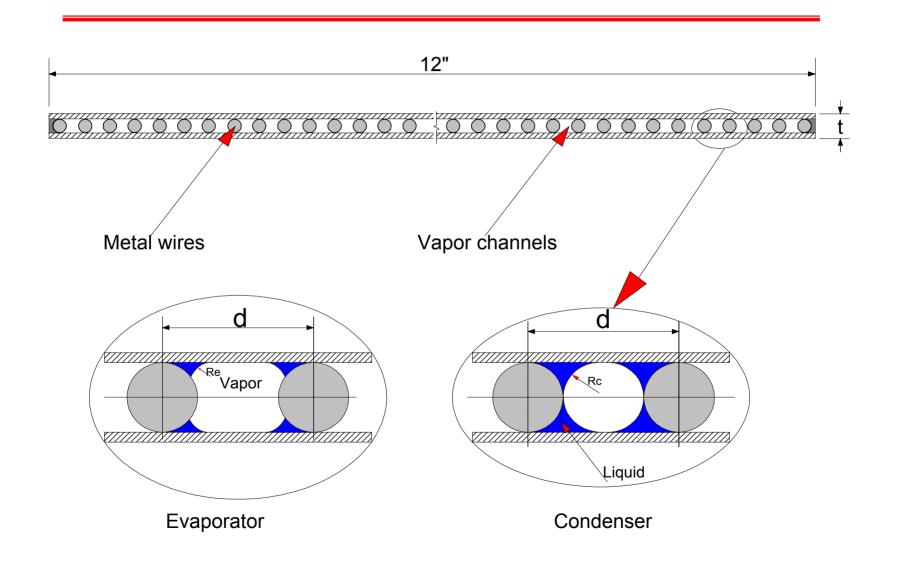


#### **Initial Concepts**

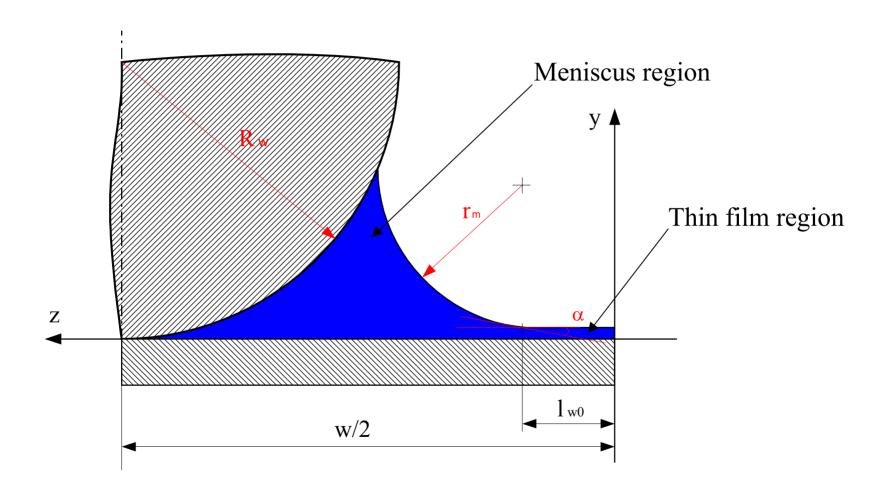
From an initial group of six concepts, the following were selected for further study

- Wire bonded heat pipe array
- Flexible Polymer Heat Pipe

# Flexible Wire Bonded Micro Heat Pipe



# **Liquid Distribution**



#### **Geometric Parameters**

$$\beta_1 + \beta_2 + \alpha = \frac{\pi}{2} \qquad R_w \sin^2 \beta_1 = r_m \cos \beta_1 \sin \beta_2$$

$$\beta_1 = a \tan \left[ \frac{1}{2R_w} \left( -r_m \sin \alpha + \left( (r_m \sin \alpha)^2 + 4R_w r_m \cos \alpha \right)^{\frac{1}{2}} \right) \right]$$

$$A_{c,l} = 2R_w r_m \sin \beta_1 \sin \beta_2 - R_w^2 (\beta_1 - \sin \beta_1 \cos \beta_2) - r_m^2 (\beta_2 - \sin \beta_2 \cos \beta_2)$$

$$A_{c,v} = R_w (2w - \pi R_w) - 4A_{c,l} \qquad l_{ac} = 2R_w \beta_1$$

$$l_{ab} = \left[ (r_m \sin \alpha)^2 + 4R_w r_m \cos \alpha \right]^{\frac{1}{2}} - r_m \sin \alpha \qquad l_{cb} = 2r_m \beta_2$$

#### Fluid Flow Model

#### **Continuity Equations**

$$\frac{d(u_{l}A_{c,l})}{dx} - v_{l,i}p_{i} = 0 \qquad \qquad \frac{d(u_{v}A_{c,v})}{dx} - v_{v,i}p_{i} = 0$$

#### **Momentum Equations**

$$-\rho_{l}(2A_{c,l}u_{l}\frac{du_{l}}{dx}+u_{l}^{2}\frac{dA_{c,l}}{dx})-A_{c,l}\frac{dP_{l}}{dx}+p_{l,i}\tau_{l,i}+p_{l,w}\tau_{l,w}-g\rho_{l}A_{c,l}\sin\theta=0$$

$$\rho_{v}(2A_{c,v}u_{v}\frac{du_{v}}{dx}+u_{v}^{2}\frac{dA_{c,v}}{dx})+A_{c,v}\frac{dP_{v}}{dx}+p_{v,i}\tau_{v,i}+p_{v,w}\tau_{v,w}+g\rho_{v}A_{c,v}\sin\theta=0$$

**Energy Equations** 

$$v_{l,i} = \frac{q''w}{2\rho_l p_{l,i} h'_{fg}}$$
  $v_{v,i} = \frac{2wq''}{\rho_v p_{v,i} h'_{fg}}$ 

#### Fluid Flow Model

The condenser exposed in radiation:

$$q_c$$
"=  $h_{c,o}(T_v - T_{\sin k})(1 + \frac{h_{c,o}}{\overline{h}_c})^{-1}$ 

$$q_a$$
"= 0

$$h_{c,o} = \varepsilon \sigma_0 (T_{w,o} + T_{\sin k}) (T_{w,o}^2 + T_{\sin k}^2)$$

In the evaporator section:

$$v_{v,i} = \frac{2wh_{c,o}(T_v - T_{\sin k})\left(1 + \frac{h_{c,o}}{\overline{h_c}}\right)^{-1}}{\rho_v p_{v,i} h_{fg}}$$

$$q_e$$
"=  $cons \tan t$ 

$$v_{l,i} = \frac{wh_{c,o}(T_v - T_{\sin k})\left(1 + \frac{h_{c,o}}{h_c}\right)^{-1}}{2\rho_l p_{l,i} h_{fg}}$$

# **Heat Transfer in the Evaporator**

Heat transfer in evaporating film:

$$\Delta Q_1 = 0$$

$$\Delta Q_{2+3} = \int_{2}^{r_{2}} \frac{T_{w,i} - T_{v}}{\frac{1}{h_{ph}} + \frac{\delta(z')}{k_{l}}} dz' \qquad \Delta Q_{2+3} = \int_{2}^{r_{2}} \frac{T_{w,i} - T_{v}}{\frac{1}{3.2\rho_{v}h_{fg}} \left(\frac{T_{v}}{R_{g}}\right)^{0.5} + \left(\frac{\delta_{0} - r_{m} + \left(r_{m}^{2} + z'^{2}\right)^{0.5}}{k_{l}}\right)} dz'$$

$$\Delta Q_{4} = \int_{2}^{2r_{m}\sin\beta_{1}\sin\beta_{2}} \frac{(T_{w,i} - T_{v})}{(1/h_{ph} + z'^{2}/2r_{m}k_{l})} dz' \qquad \qquad \overline{h}_{ph} = 3.2\rho_{v}h_{fg}\sqrt{\frac{R_{g}}{T_{v}}}$$

$$= 1.41(T_{w,i} - T_{v})(h_{pc}k_{l}r_{m})^{\frac{1}{2}} \left[\frac{\pi}{2} - a\tan\left(\frac{h_{ph}\delta_{2}}{k_{l}}\right)^{\frac{1}{2}}\right] \qquad \qquad h_{e,men} = \frac{\Delta Q_{2+3} + \Delta Q_{4}}{(T_{w,i} - T_{v})l_{ab}}$$

$$\overline{h}_{e} = \left\{ \left[ \frac{2l_{ab}}{w} h_{e,men} \right]^{-1} + \frac{t_{w}}{k_{w}} \right\}^{-1} \qquad T_{w,o} = T_{\sin k} + \frac{T_{v} - T_{\sin k}}{h_{o,e}} \left( \frac{1}{h_{o,e}} + \frac{1}{\overline{h}_{i,e}} \right)^{-1}$$

#### **Heat Transfer in the Condenser**

The thickness of the condensed liquid film:

$$-\frac{\sigma\delta^{3}}{3v_{l}}\frac{d^{3}\delta}{dz^{3}} = \frac{k_{l}\left(T_{sat} - T_{w}\right)}{h_{fo}} \int_{0}^{z} \frac{1}{\delta}dz \qquad \text{B.C:} \quad \frac{d\delta}{dz}\bigg|_{z=0} = 0 \qquad \frac{d^{3}\delta}{dz^{3}}\bigg|_{z=0} = 0$$

Assuming the thickness of liquid film:

$$\left. \frac{d^2 \delta}{dz^2} \right|_{z=l_{w0}} = \frac{1}{r_m} \qquad \left. \frac{d \delta}{dz} \right|_{z=l_{w0}} = \tan \alpha$$

$$\frac{\delta}{w} = C_0 + C_1 \frac{z}{w} + C_2 \frac{z^2}{w^2} + C_3 \frac{z^3}{w^3} + C_4 \frac{z^4}{w^4}$$

$$\overline{h}_{c,f} = \frac{k_l}{\overline{\delta}} \qquad \overline{h}_{c,f} = \frac{k_l}{wC_0} = \left[ \frac{h_{fg} \rho_l \sigma k_l^3 (l_{w0} / r_m - \tan \alpha)}{\mu_l l_{w0}^3 (T_v - T_w)} \right]^{\frac{1}{4}}$$

#### **Heat Transfer in the Condenser**

Film thickness of the liquid meniscus:

$$\delta = \delta \Big|_{s=l_{w0}} + r_m \cos \alpha - \left[ (r_m \cos \alpha)^2 - (z - l_{w0})^2 - 2r_m (z - l_{w0}) \sin \alpha \right]^{\frac{1}{2}}$$

Heat transfer coefficient in meniscus:

$$\overline{h}_{c,men} = \int_{w_0}^{2r_m \sin \beta_1 \sin \beta_2} \frac{k_l}{l_{ab} \left\{ \delta \Big|_{s=l_{w_0}} + r_m \cos \alpha - \left[ (r_m \cos \alpha)^2 - (z - l_{w_0})^2 - 2r_m (z - l_{w_0}) \sin \alpha \right]^{0.5} \right\}} dz$$

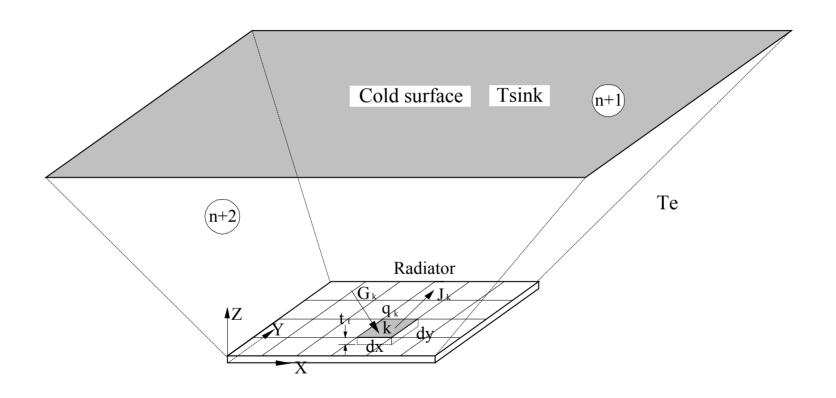
Heat transfer coefficient in the condenser

$$\overline{h}_{c} = \left\{ \left[ \frac{2l_{w0}}{w} \overline{h}_{c,f} + (1 - \frac{2l_{w0}}{w}) \overline{h}_{c,men} \right]^{-1} + \frac{t_{w}}{k_{w}} \right\}^{-1}$$

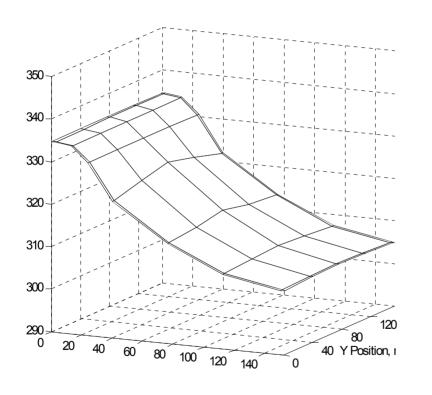
$$T_{w,o} = T_{c,o} + (T_v - T_{c,o}) \frac{1}{h_{c,o}} \left(\frac{1}{h_{c,o}} + \frac{1}{\overline{h}_c}\right)^{-1}$$

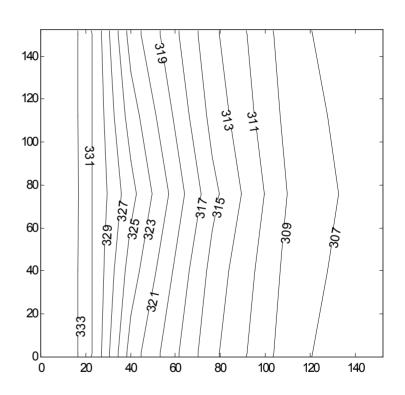
$$h_{c,o} = \varepsilon \sigma_0 (T_{w,o} + T_{\sin k}) (T_{w,o}^2 + T_{\sin k}^2)$$

#### **Radiation Heat Transfer**



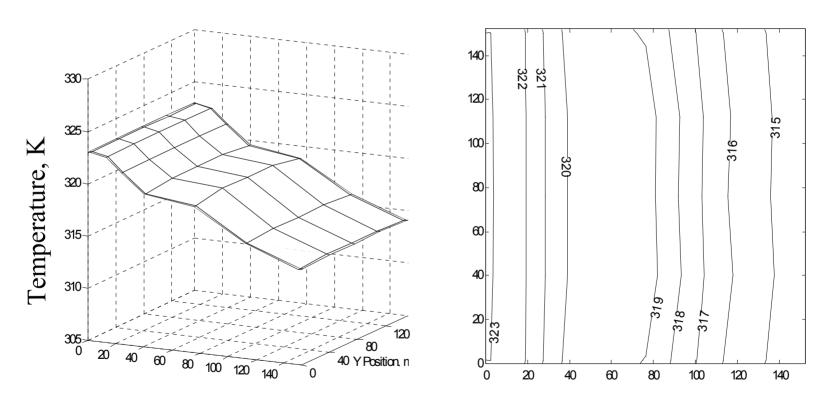
# Temperature Distributions on the Wire Bonded Micro Heat Pipe Radiator





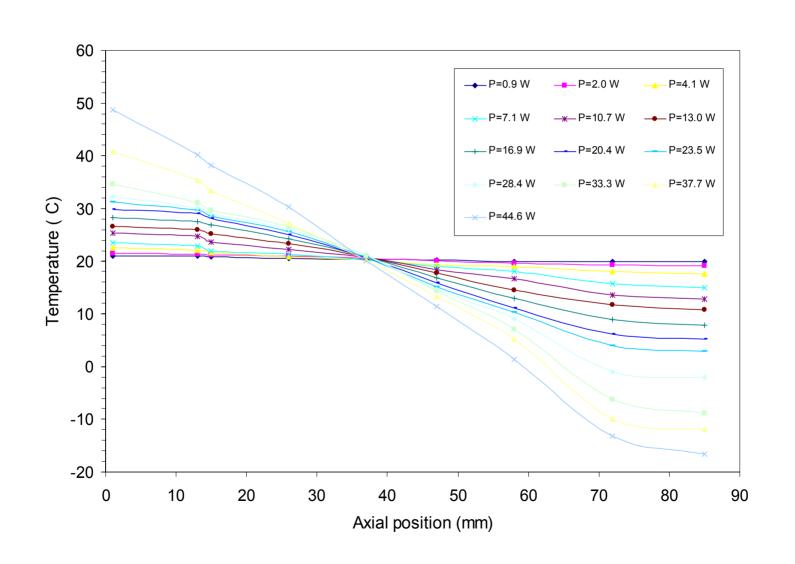
No fluid charge, dw=0.813 mm

# Temperature Distributions on the Wire Bonded Micro Heat Pipe Radiator

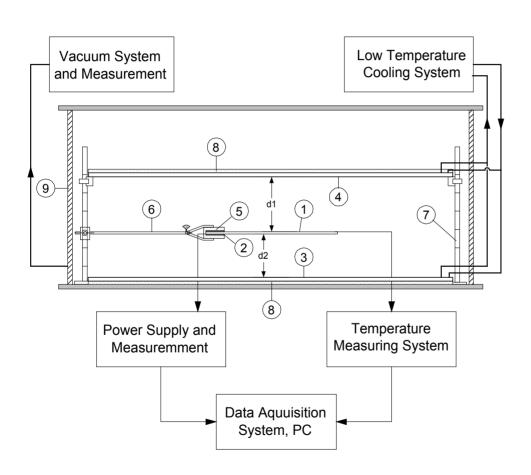


Charged with optimum charge, dw=0.813 mm

# **Axial Temperature Distribution**



#### **Test Facility for Radiation Environment**



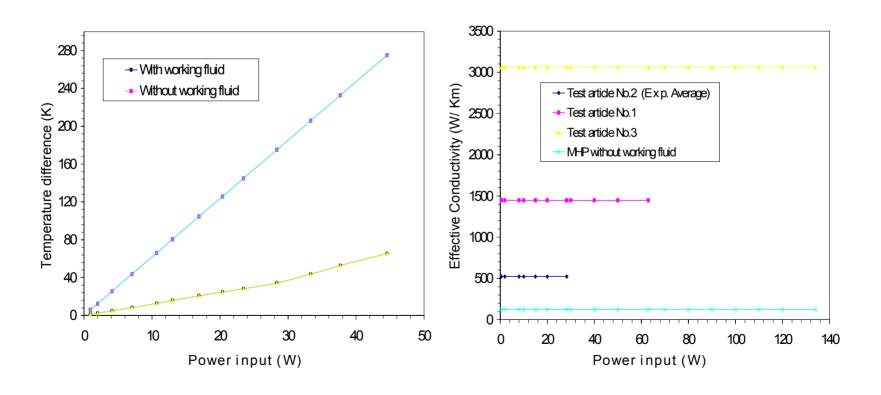
- 1. Micro heat pipe radiator
- 2. Electric heater
- 3. Bottom cold plate
- 4. Top cold plate
- 5. Electric heater insulation
- 6. Adjustable support level
- 7. Adjustable support feet
- 8. Insulation material
- 9. Vacuum chamber

#### **Test Articles**

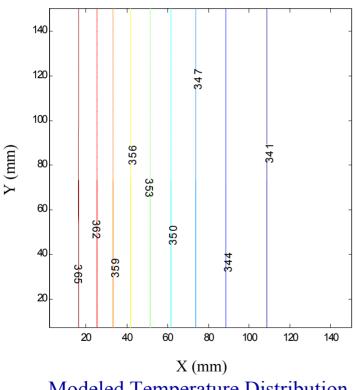
Prototype	No. 1	No. 2	No. 3
Material	Aluminum	Aluminum	Aluminum
Working fluid	Acetone	Acetone	Acetone
Total Dimension	152×152.4	152×152.4	152×152.4
(mm)			
Thickness of sheet	0.40	0.40	0.40
(mm)			
Diameter of wire	0.50	0.80	0.50
(mm)			
Number of wires	43	43	95

#### **Experimental Results**

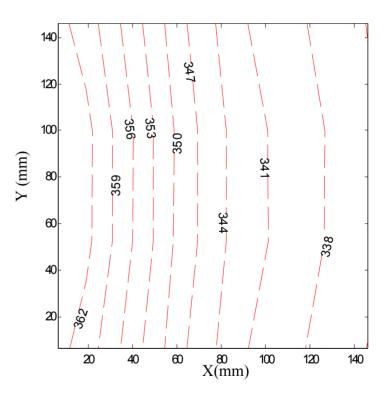
#### Effective Thermal Conductivity



# Comparison of Experimental and Predicted Results

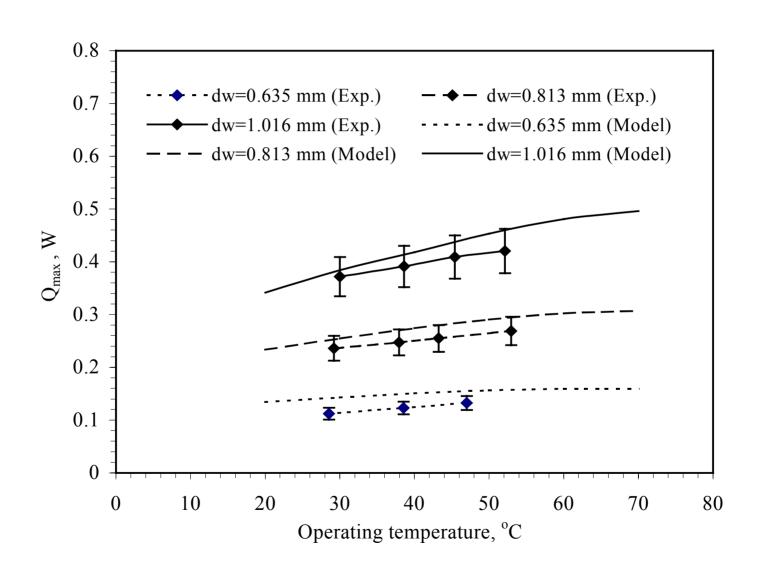


Modeled Temperature Distribution

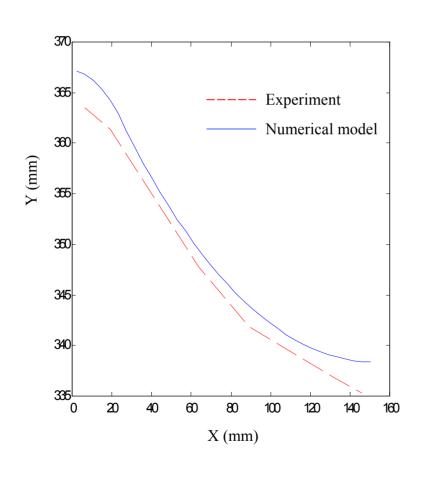


Measured Temperature Distribution

#### Comparison of the Predicted Experimental Results

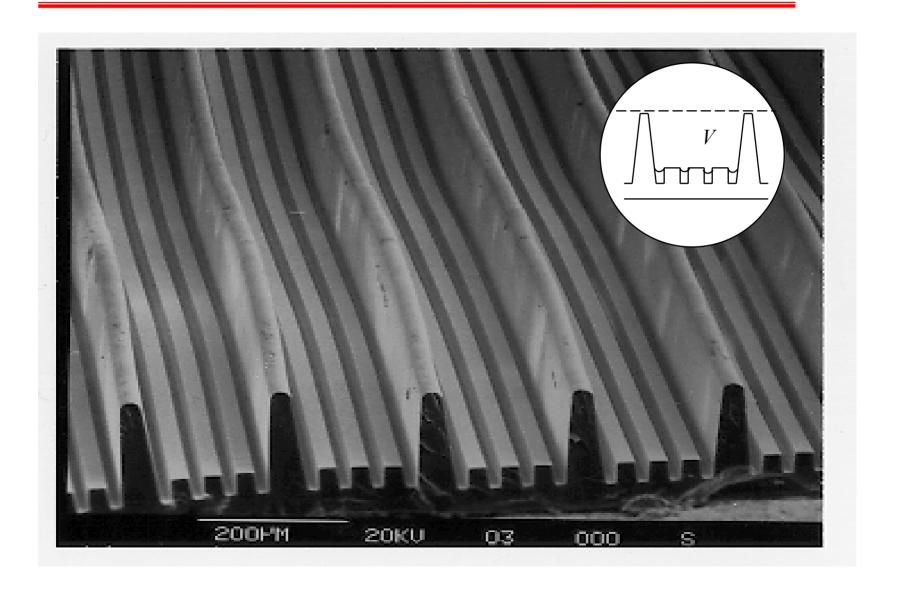


#### Comparison of Experimental and Predicted Results

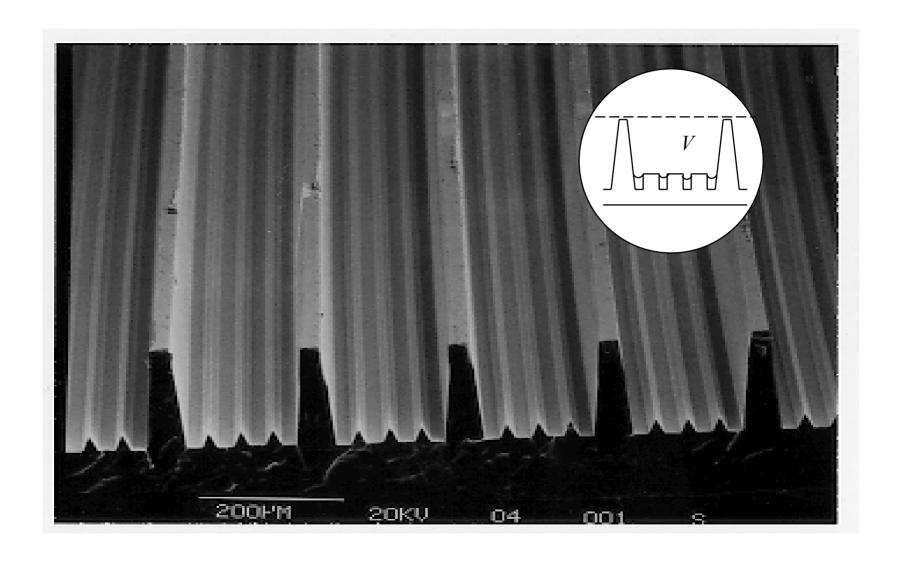


- Temperature distribution obtained from the experiment was slightly lower than from the model.
- Heat loss may result from conduction through the support and insulation and edge radiation
- Total difference is less than 6.8%

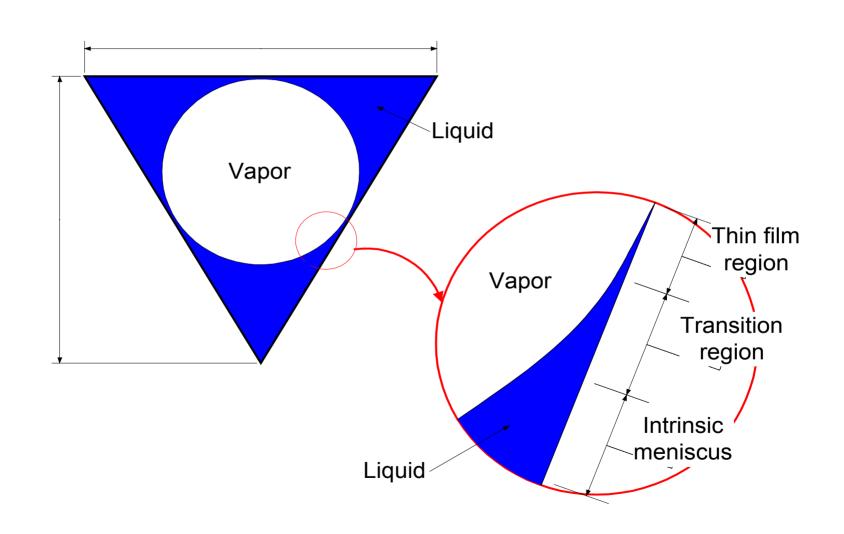
# Rectangular Polymer Heat Pipe



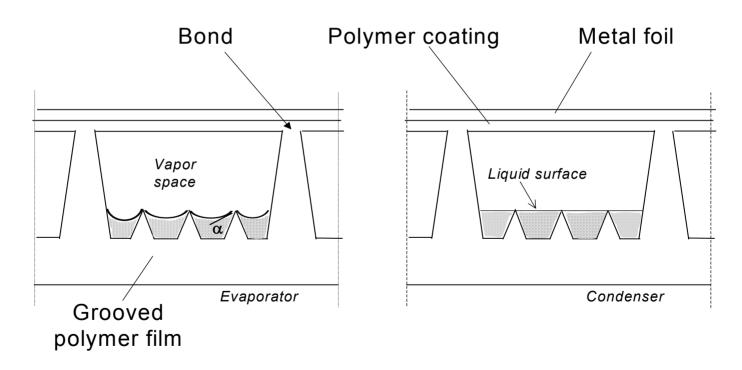
# Triangular Polymer Heat Pipe



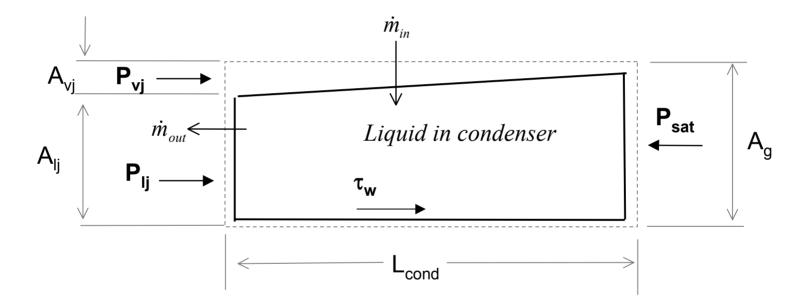
# **Interfacial Region**



# **Polymer Micro Heat Pipe**



#### **Momentum Balance**



#### **Numerical Model**

The governing equation for two-dimensional plate conduction combined with a radiation boundary condition can be expressed as,

$$\frac{\partial}{\partial x}(ttk_{eff,x}\frac{\partial T}{\partial x}) + \frac{\partial}{\partial y}(ttk_{eff,y}\frac{\partial T}{\partial y}) - q_k + q_0 = 0$$
(1)

if  $q_k$  is the net radiation transfer through the control volume k, this equation can be expressed as,

$$\sum_{j=1}^{n+2} \left( \frac{\delta_{kj}}{\varepsilon_j} - F_{k-j} \frac{1 - \varepsilon_j}{\varepsilon_j} \right) q_j = \sum_{j=1}^{n+2} \left( \delta_{kj} - F_{k-j} \right) \sigma T_j^4$$
(2)

where  $\delta_{ki}$  is the Kronecker delta defined as,

$$\mathcal{S}_{kj} = \begin{cases} 1 & \text{when} & k=j \\ 0 & \text{when} & k \neq j \end{cases}$$

#### **Numerical Model**

For the case of constant thermal effective conductivity for the micro heat pipe array, Eq. (1) becomes,

$$K_{eff,x} \frac{\partial^2 T}{\partial x^2} + K_{eff,y} \frac{\partial^2 T}{\partial y^2} - q_k + q_0 = 0$$
(3)

where  $K_{eff,x}$ = t  $k_{eff,x}$ , and  $K_{eff,y}$ = t  $k_{eff,y}$ The discretization equation is,

$$a_{1}T_{i-1,j}^{n} - a_{2}T_{i,j}^{n} + a_{1}T_{i+1,j}^{n} = c_{1} - c_{2}(T_{i,j}^{n-1} + T_{i,j-1}^{n-1})$$

$$(4)$$

where

$$a_{1} = \frac{K_{eff,x}}{\Delta x^{2}},$$
  $a_{2} = 2(\frac{K_{eff,x}}{\Delta x^{2}} + \frac{K_{eff,y}}{\Delta y^{2}})$ 

$$c_{1} = (q_{k} - q_{0}),$$
  $c_{2} = \frac{K_{eff,y}}{\Delta y^{2}}$ 

#### **Numerical Model**

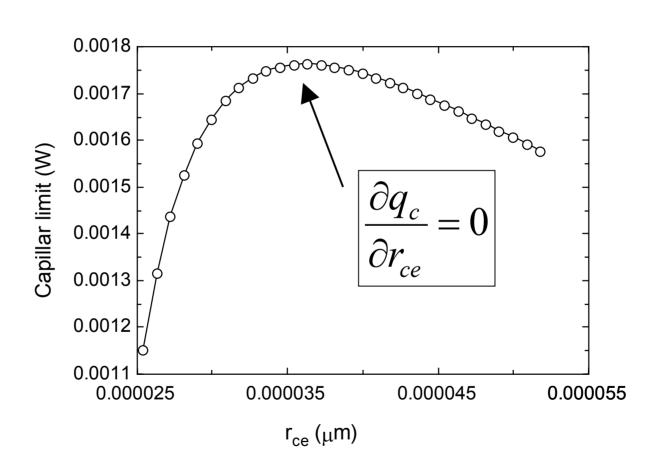
Adiabatic boundary condition on the edges are assumed, i.e.,

$$\frac{\partial T}{\partial x} = 0 \begin{cases} at \ x = 0, & 0 \le y \le 152.4 mm \\ at \ x = 152 mm, & 0 \le y \le 152.4 mm \end{cases}$$

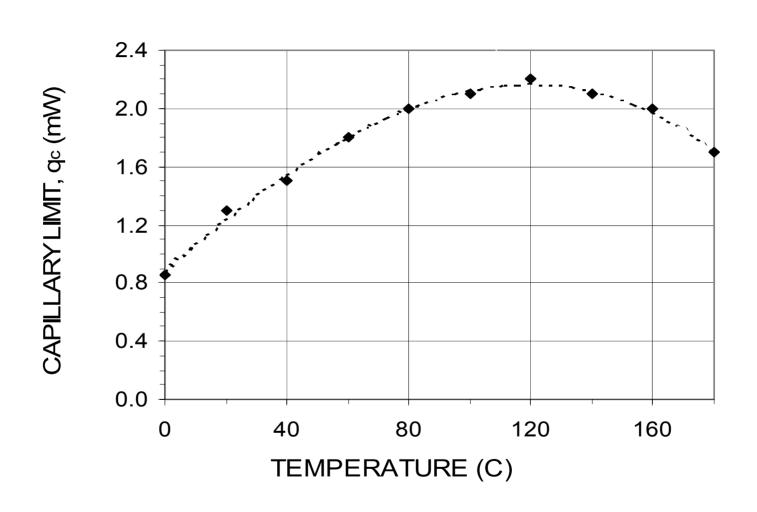
$$\frac{\partial T}{\partial y} = 0 \begin{cases} at \ y = 0, & 0 \le x \le 152 mm \\ at \ y = 1524 mm, & 0 \le x \le 152 mm \end{cases}$$
and
$$q_0 = q_{\text{input}}, & 0 \ x \le 25.4 \ \text{mm}, & 0 \le y \le 152.4 \ \text{mm}$$

 $q_0=0$ , x > 25.4 mm,  $0 \le y \le 152.4$  mm

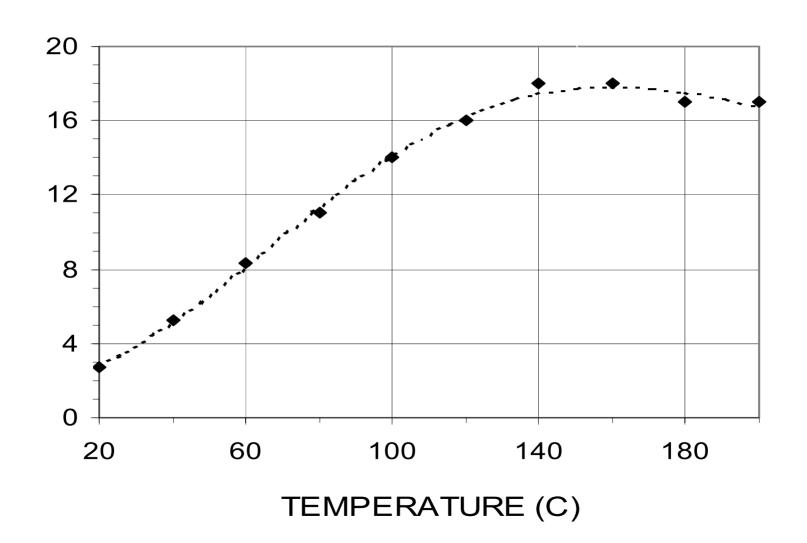
# **Optimum Capillary Radius**



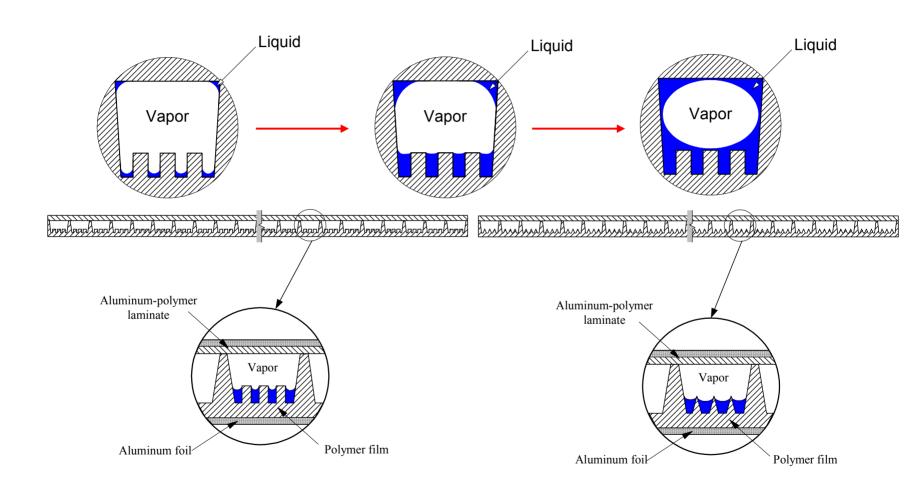
# **Capillary Limit - Methanol**



# **Capillary Limit Water**



# **Stable Liquid Configurations**



#### **Summary and Conclusions**

- Two new micro heat pipe concepts have been developed
- Wire Bonded heat pipe arrays with an effective conductivity of 30 times that of solid aluminum have been developed and tested.
- Flexible polymer heat pipes have been fabricated and modeled.
- These polymer heat pipes offer a greater degree of flexibility and a potentially higher effective thermal conductivity than any previously developed.
- Applications of the these two concepts have a wide range of applications that extends well beyond spacecraft radiators.